Journal of Inorganic and Organometallic Polymers and Materials, Vol. 17, No. 1, March 2007 (© 2007)
DOI: 10.1007/s10904-007-9105-8

A Study of Encapsulation Resin Containing Hexagonal Boron Nitride (hBN) as Inorganic Filler

Tzu Hsuan Chiang,[1] and T.-E. Hsieh[1,2]

ERRATUM TO: JOURNAL OF INORGANIC AND ORGANOMETALLIC POLYMERS AND MATERIALS DOI: 10.1007/s10904-006-9037-8

The submitted and accepted dates for this paper were inadvertently omitted. The dates are as follows:

Submitted August 23, 2005; accepted November 22, 2005

The online version of the original article can be found at: http://dx.doi.org/10.1007/s10904-006-9037-8

[1] Department of Materials Science and Engineering, National Chiao Tung University, 1001 Ta-Hsueh Road, Hsinchu, 30050, Taiwan ROC.
[2] To whom correspondence should be addressed.
E-mail: tehsieh@cc.nctu.edu.tw

1574-1443/07/0300-0335/0 © 2007 Springer Science+Business Media, LLC